



ABSTRACT OF THE DISCLOSURE

5 It is an object of the invention to provide
film peeling method and device which, when a
circuit board with laminated thin films coated on
the front and back surfaces thereof is beaten by
vibrator rods from the front and back sides thereof
to thereby peel the film, can absorb variations in
the coated positions of the front and back
laminated thin films and also prevent the vibrator
10 rods from being damaged when they beat each other
idly.

Vibrators 16A, 16B are disposed on the front
and back sides of a circuit board 14 with laminated
thin films 12A, 12B coated on the front and back
15 surfaces thereof, back and front back-up rollers
24B, 24A are disposed at positions respectively
opposed to the front and back rods 18A, 18B of the
vibrators 16A, 16B, and the back and front back-up
rollers 24B, 24A are moved synchronously with the
20 front and back rods 18A, 18B, respectively.